

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No.: SEMT116964

Application No.: 10/687,112

B. Kim

Group Art Unit: 1762

Filed:

October 15, 2003

Examiner: F.J. Parker

Title:

PROCESSES AND TOOLS FOR FORMING LEAD-FREE

ALLOY SOLDER PRECURSORS

INFORMATION DISCLOSURE STATEMENT

March 9, 2004

TO THE COMMISSIONER FOR PATENTS:

Applicant is aware of the information listed in the attached form that may be material to the prosecution of the above-identified patent application.

- Pursuant to 37 C.F.R. § 1.97(b), this Information Disclosure Statement is being 1. X filed before the mailing date of a first Office Action on the merits.
- 2. The Commissioner is hereby authorized to charge any fees under 37 C.F.R. X §§ 1.16, 1.17 and 1.18 which may be required during the entire pendency of the application, or credit any overpayment, to Deposit Account No. 03-1740. This authorization also hereby includes a request for any extensions of time of the appropriate length required upon the filing of any reply during the entire prosecution of this application.

Respectfully submitted,

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I hereby certify that this correspondence is being deposited with the U.S. Postal Service in a sealed envelope as first class mail with postage thereon fully prepaid and addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the below date.

Shannon

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INFORMATION CITED BY APPLICANT THAT MAY BE MATERIAL TO THE PROSECUTION OF THE SUBJECT APPLICATION

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U.S. PATENT DOCUMENTS

*Examiner Initials	Cite No.	Document No.	Kind Code	Date (mm/dd/yyyy)	Name
	U1	5,902,472	Α	05/11/1999	Arai et al.
	U2	5,940,235	Α	08/17/1999	Sasaki et al.
	U3	5,948,235	Α	09/07/1999	Arai
*Examiner Initial	OTHER INFORMATION (Including Author, Title, Date, Pertinent Pages, Etc.) Cite No.				
	O1	Kim, B., and T. Ritzdorf, "Electrochemically Deposited Tin-Silver-Copper Ternary Solder Alloys," <i>Journal of The Electrochemical Society 150</i> (2):C53-C60, 2002.			
	O2	Kim, B., and T. Ritzdorf, "Electrodeposition of Ternary Near-Eutectic SnAgCu Solders With an Alkaline Bath," <i>Proceedings of the 2002 International Symposium and Exhibition on Advanced Packaging Materials, Session 3</i> , Stone Mountain Park, Georgia, March 3-6, 2002.			

Examiner	Date Considered

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^{*}Examiner: Initial if reference considered, whether or not citation is in conformance with M.P.E.P. § 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.